



3-PIN SUPPLY VOLTAGE SUPERVISORS

Check for Samples: [TPS3809J25](#), [TPS3809L30](#), [TPS3809K33](#), [TPS3809I50](#)

FEATURES

- 3-Pin SOT-23 Package
- Supply Current of 9 μ A (Typical)
- Precision Supply Voltage Monitor
2.5 V, 3 V, 3.3 V, 5 V
- Pin-For-Pin Compatible With MAX 809
- Temperature Range: -40°C to $+85^{\circ}\text{C}$

APPLICATIONS

- Applications Using DSPs, Microcontrollers, or Microprocessors
- Wireless Communication Systems
- Portable/Battery-Powered Equipment
- Programmable Controls
- Intelligent Instruments
- Industrial Equipment
- Notebook/Desktop Computers
- Automotive Systems

DESCRIPTION

The TPS3809 family of supervisory circuits provides circuit initialization and timing supervision, primarily for DSPs and processor-based systems.

During power-on, $\overline{\text{RESET}}$ is asserted when the supply voltage V_{DD} becomes higher than 1.1 V. Thereafter, the supervisory circuit monitors V_{DD} and keeps $\overline{\text{RESET}}$ active as long as V_{DD} remains below the threshold voltage V_{IT} . An internal timer delays the return of the output to the inactive state (high) to ensure proper system reset. The delay time, $t_{\text{d(typ)}} = 200$ ms, starts after V_{DD} has risen above the threshold voltage V_{IT} . When the supply voltage drops below the threshold voltage V_{IT} , the output becomes active (low) again. No external components are required. All the devices of this family have a fixed sense-threshold voltage V_{IT} set by an internal voltage divider.

The product spectrum is designed for supply voltages of 2.5 V, 3 V, 3.3 V, and 5 V. The circuits are available in a 3-pin SOT-23. The TPS3809 devices are characterized for operation over a temperature range of -40°C to 85°C .

**Figure 1. DBV PACKAGE
TOP VIEW)**

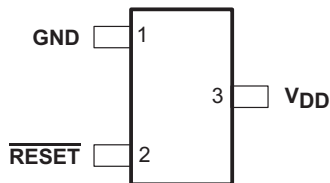
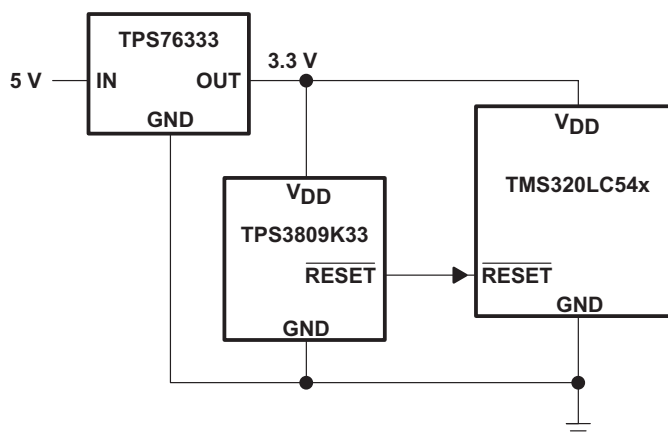


Figure 2. Typical Application



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

AVAILABLE OPTIONS⁽¹⁾

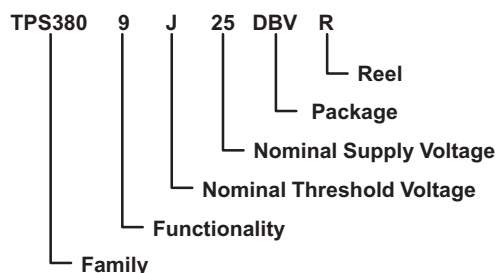
T _A	DEVICE NAME		THRESHOLD VOLTAGE	MARKING
–40°C to 85°C	TPS3809J25DBVR	TPS3809J25DBVT	2.25 V	PCZI
	TPS3809L30DBVR	TPS3809L30DBVT	2.64 V	PDAI
	TPS3809K33DBVR	TPS3809K33DBVT	2.93 V	PDBI
	TPS3809I50DBVR	TPS3809I50DBVT	4.55 V	PDCI

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this data sheet, or refer to our web site at www.ti.com.

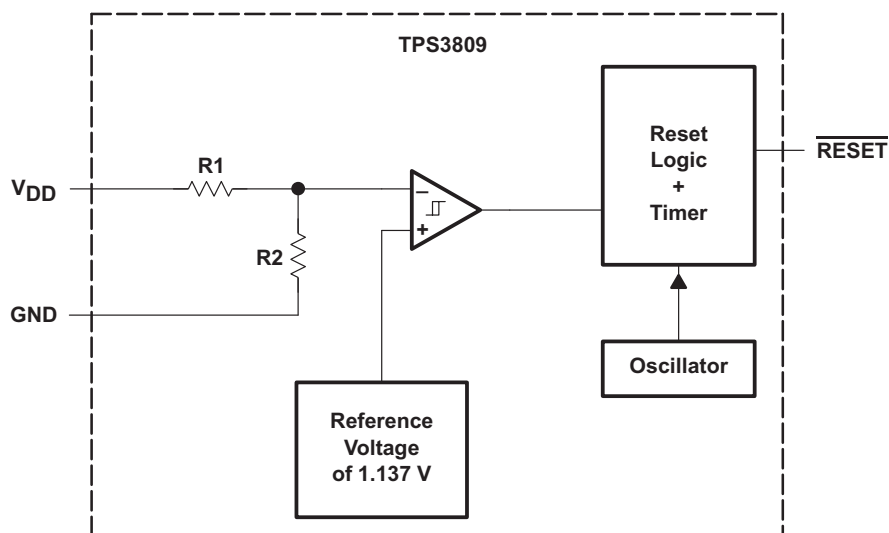
FUNCTION/TRUTH TABLE, TPS3809

V _{DD} >V _{IT}	$\overline{\text{RESET}}$
0	L
1	H

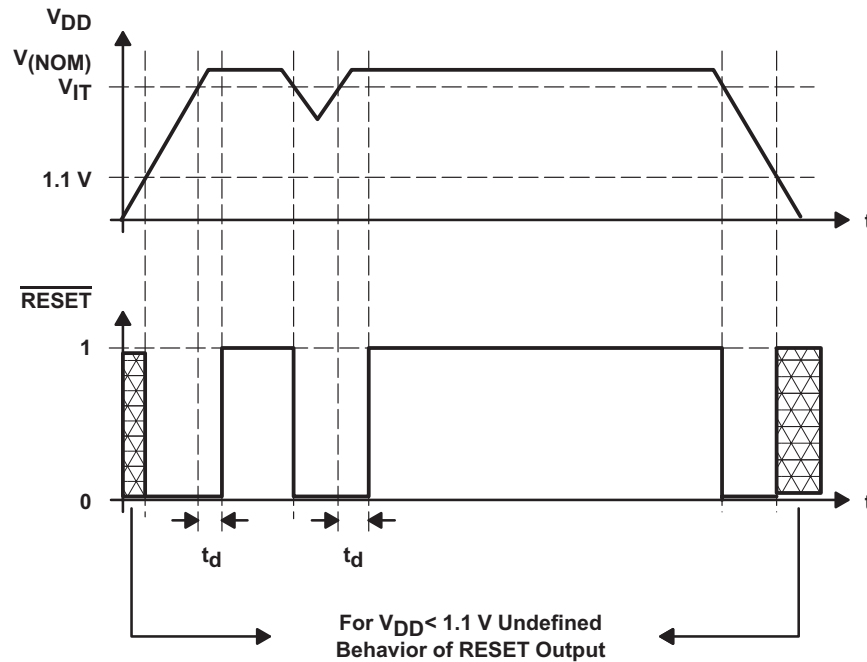
ORDERING INFORMATION



FUNCTIONAL BLOCK DIAGRAMS



TIMING DIAGRAM



ABSOLUTE MAXIMUM RATINGS^{(1) (2)}

Over operating free-air temperature range (unless otherwise noted).

	UNIT
Supply voltage, V_{DD}	7 V
All other pins	–0.3 V to 7 V
Maximum low-output current, I_{OL}	5 mA
Maximum high-output current, I_{OH}	–5 mA
Input-clamp current, I_{IK} ($V_I < 0$ or $V_I > V_{DD}$)	±20 mA
Output-clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{DD}$)	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating junction temperature range, T_A	–40°C to 85°C
Storage temperature range, T_{stg}	–65°C to 150°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to GND. For reliable operation, the device should not be operated at 7 V for more than $t = 1000\text{h}$ continuously.

DISSIPATION RATINGS

PACKAGE	$T_A < 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A < 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING
DBV	437 mW	3.5 mW/°C	280 mW	227 mW

RECOMMENDED OPERATING CONDITIONS

	MIN	MAX	UNIT
Supply voltage, V_{DD}	2	6	V
$\overline{\text{RESET}}$ current sink during startup		50	μA
Operating free-air temperature range, T_A	–40	+85	°C

ELECTRICAL CHARACTERISTICS

Overrecommended operating free-air temperature range (unless otherwise noted).

PARAMETER		TEST CONDITIONS	TPS3800-xx, TPS3801-xx, TPS3802-xx			UNIT
			MIN	TYP	MAX	
V _{OH} High-level output voltage		V _{DD} = 2.5 V to 6 V I _{OH} = –500 µA	V _{DD} –0.2			V
		V _{DD} = 3.3 V I _{OH} = –2 mA	V _{DD} –0.4			
		V _{DD} = 6 V I _{OH} = –4 mA	V _{DD} –0.4			
V _{OL} Low-level output voltage		V _{DD} = 2 V to 6 V, I _{OL} = 500 µA			0.2	V
		V _{DD} = 3.3 V, I _{OL} = 2 mA			0.4	
		V _{DD} = 6 V, I _{OL} = 4 mA			0.4	
Power-up reset voltage ⁽¹⁾		V _{DD} ≥ 1.1 V, I _{OL} = 50 µA			0.2	V
V _{IT–} Negative-going input threshold voltage ⁽²⁾	TPS3809J25	T _A = –40°C to 85°C	2.2	2.25	2.3	V
	TPS3809L30		2.58	2.64	2.7	
	TPS3809K33		2.87	2.93	2.99	
	TPS3809I50		4.45	4.55	4.65	
V _{hys} Threshold hysteresis	TPS3809J25			30		mV
	TPS3809L30			35		
	TPS3809K33			40		
	TPS3809I50			60		
I _{DD} Supply current		V _{DD} = 2 V, output unconnected		9	12	µA
		V _{DD} = 6 V, output unconnected		20	25	
C _i Input capacitance		V _I = 0 V to V _{DD}		5		pF

(1) The lowest supply voltage at which $\overline{\text{RESET}}$ becomes active. t_r , V_{DD} ≥ 15 µs/V.

(2) To ensure the best stability of the threshold voltage, a bypass capacitor (0.1-µF ceramic) should be placed near the supply terminals.

TIMING REQUIREMENTS

at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

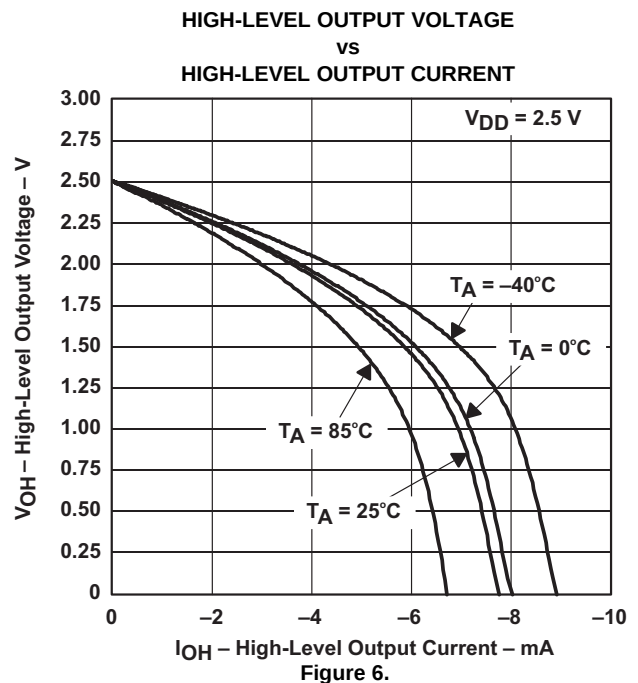
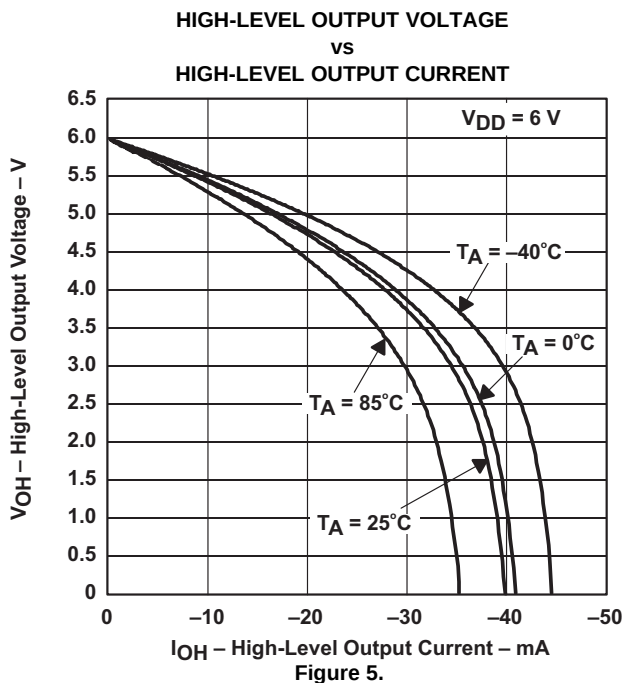
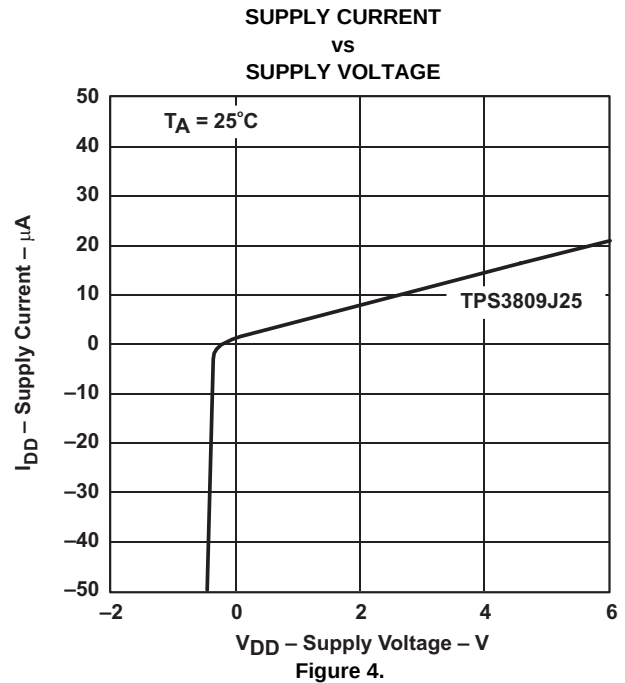
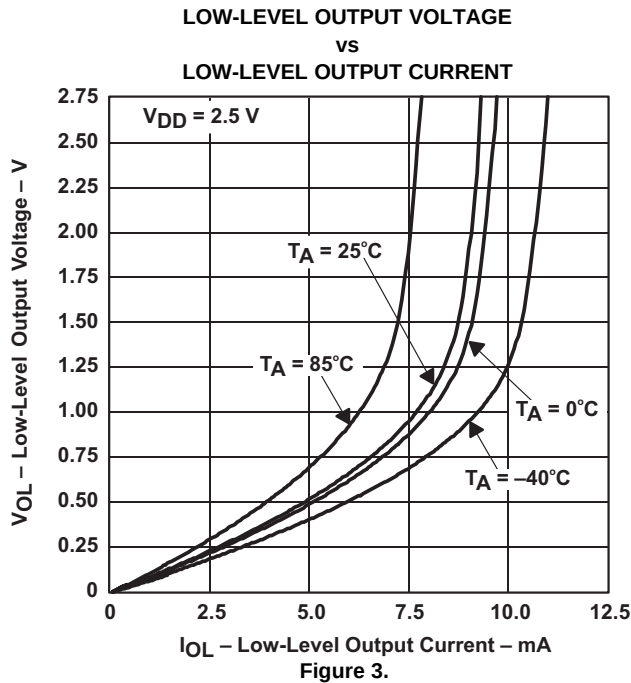
PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _w Pulse width	at V _{DD}	V _{DD} = V _{IT–} + 0.2 V, V _{DD} = V _{IT–} –0.2 V	3			µs

SWITCHING CHARACTERISTICS

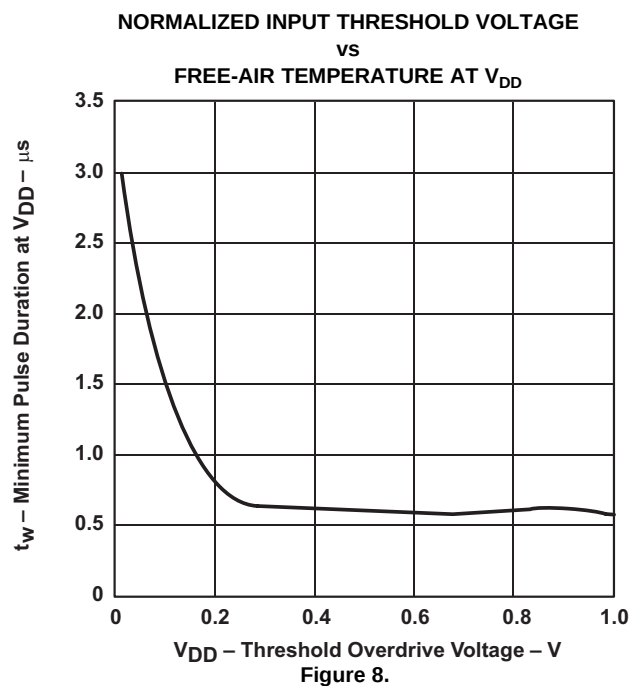
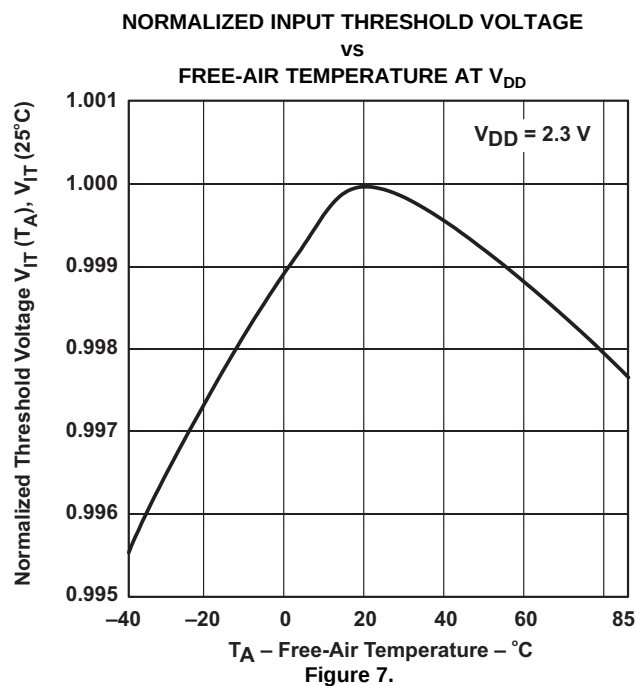
at R_L = 1 MΩ, C_L = 50 pF, T_A = 25°C

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t _d Delay time		V _{DD} ≥ V _{IT–} + 0.2 V, See timing diagram	120	200	280	ms
t _{PHL} Propagation (delay) time, high-to-low-level output	V _{DD} to $\overline{\text{RESET}}$ delay	V _{IL} = V _{IT–} – 0.2 V, V _{IH} = V _{IT–} + 0.2 V		1		µs

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS (continued)



REVISION HISTORY

Changes from Original (August 1999) to Revision A	Page
• Added Pull-up resistor value, $\overline{\text{RESET}}$ to the Recommended Operating Conditions Table	3
Changes from Revision A (October 2010) to Revision B	Page
• Changed the Pull-up resistor value, $\overline{\text{RESET}}$ To: $\overline{\text{RESET}}$ current sink during startup in the Recommended Operating Conditions Table	3

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TPS3809I50DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809I50DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809I50DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809I50DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809J25DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809J25DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809J25DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809J25DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809K33DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809K33DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809K33DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809K33DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809L30DBVR	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809L30DBVRG4	ACTIVE	SOT-23	DBV	3	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809L30DBVT	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TPS3809L30DBVTG4	ACTIVE	SOT-23	DBV	3	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF TPS3809I50, TPS3809J25, TPS3809K33, TPS3809L30 :

● Automotive: [TPS3809I50-Q1](#), [TPS3809J25-Q1](#), [TPS3809K33-Q1](#), [TPS3809L30-Q1](#)

● Enhanced Product: [TPS3809I50-EP](#), [TPS3809K33-EP](#), [TPS3809L30-EP](#)

NOTE: Qualified Version Definitions:

- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product - Supports Defense, Aerospace and Medical Applications

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS3809I50DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809I50DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809J25DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809J25DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33DBVR	SOT-23	DBV	3	3000	180.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809K33DBVT	SOT-23	DBV	3	250	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3
TPS3809L30DBVR	SOT-23	DBV	3	3000	178.0	9.0	3.3	3.2	1.47	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

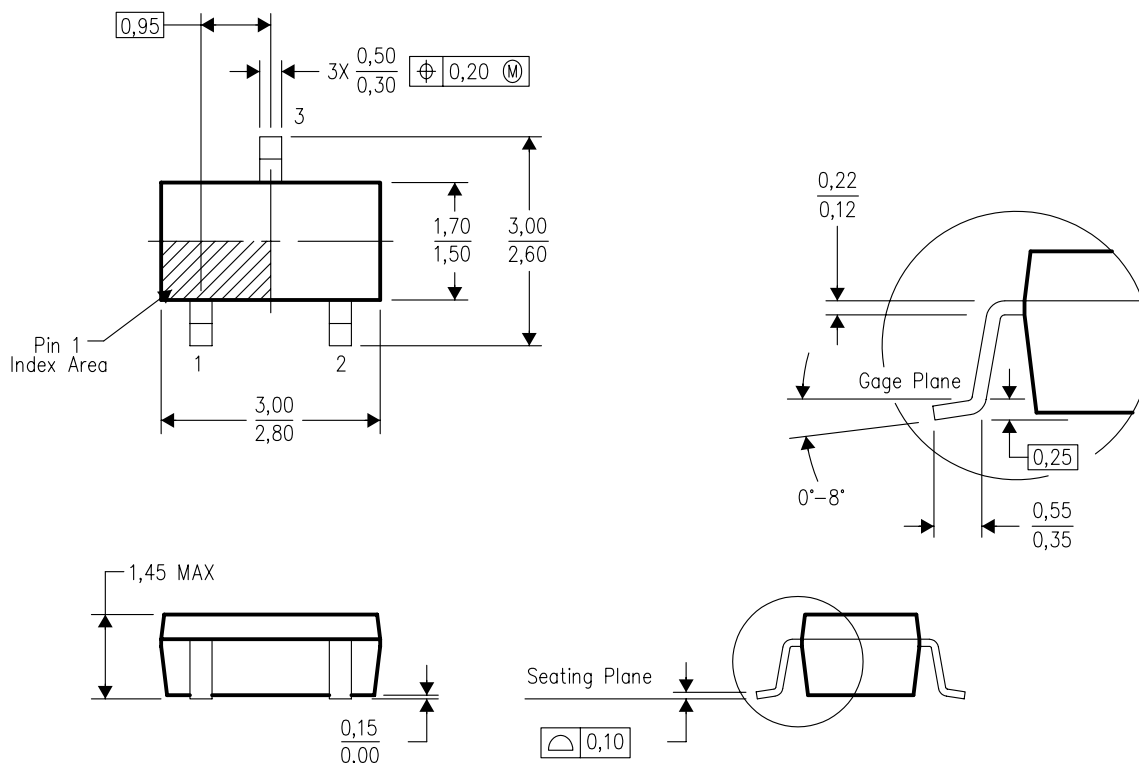


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS3809I50DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809I50DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809J25DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809J25DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809K33DBVR	SOT-23	DBV	3	3000	182.0	182.0	20.0
TPS3809K33DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0
TPS3809K33DBVT	SOT-23	DBV	3	250	180.0	180.0	18.0
TPS3809L30DBVR	SOT-23	DBV	3	3000	180.0	180.0	18.0

DBV (R-PDSO-G3)

PLASTIC SMALL-OUTLINE PACKAGE

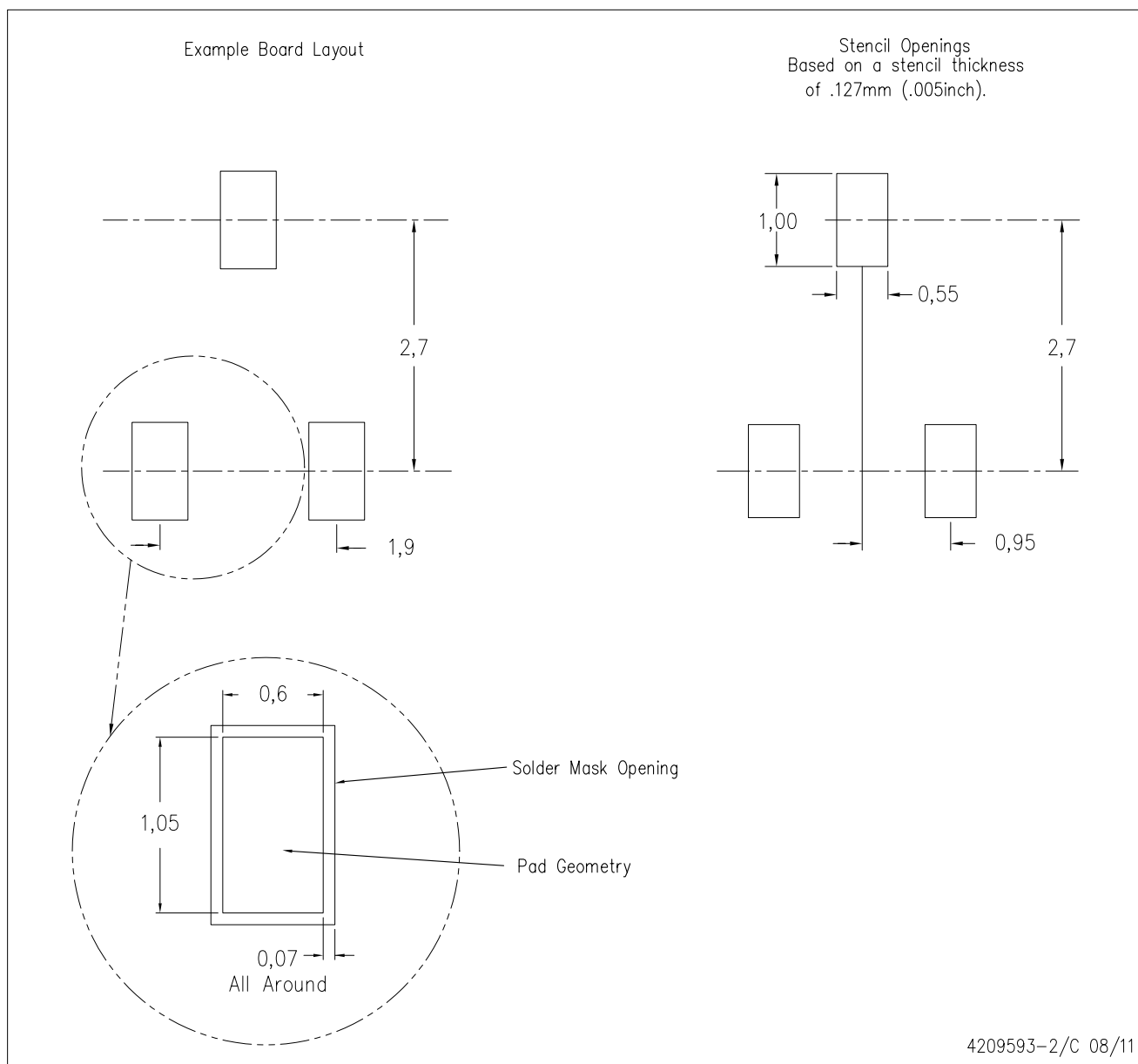


4073253-2/K 03/2006

- NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.

DBV (R-PDSO-G3)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

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